

**Features**

- Size 0.18\*0.12 inch /4.5\*3.2 mm
- Surface mount resettable fuse
- Fast time-to-trip
- Low resistance
- RoHS compliant, lead-free and halogen-free
- Compatible with high temperature solders

**Electrical Characteristics (25°C)/电性参数**

Part Number	Marking	$I_{hold}$ (A)	$I_{trip}$ (A)	$V_{max}$ (Vdc)	$I_{max}$ (A)	$P_d$ typ. (W)	Time to Trip (Max.)		Resistance	
							Current (A)	Time (Sec)	$R_{min}$ (Ω)	$R_{1max}$ (Ω)
1812L300/24GR		3.00	6.00	24	20	1.0	15.00	5.00	0.001	0.015

$I_{hold}$  = Hold current: maximum current device will pass without tripping in 25°C still air. 保持电流=在25°C静止空气环境中元件不动作的最大电流。

$I_{trip}$  = Trip current: minimum current at which the device will trip in 25°C still air. 动作电流=在25°C静止空气环境中元件的最小动作电流。

$V_{max}$  = Maximum voltage device can withstand without damage at rated current ( $I_{max}$ ). 最大电压=元件在额定电流下能承受的最大电压。

$I_{max}$  = Maximum fault current device can withstand without damage at rated voltage ( $V_{max}$ ). 最大电流=元件在额定电压下能承受的最大电流。

$P_d$  typ. = Typical power dissipated from device when in the tripped state at 25°C still air. 动作功率=在25°C静止空气环境中元件动作状态下的消耗功率。

$T_{trip}$  = Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec. 动作时间=5倍保持电流下的最大动作时间。

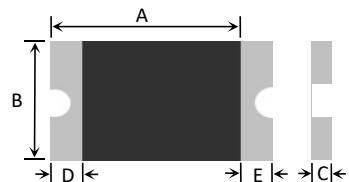
$R_{min}$  = Minimum resistance of device in initial (un-soldered) state. 初始最小电阻=元件焊接前的初始最小阻值。

$R_{1max}$  = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec. 焊后最大电阻=元件焊接1小时后的最大阻值。

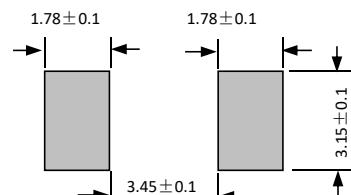
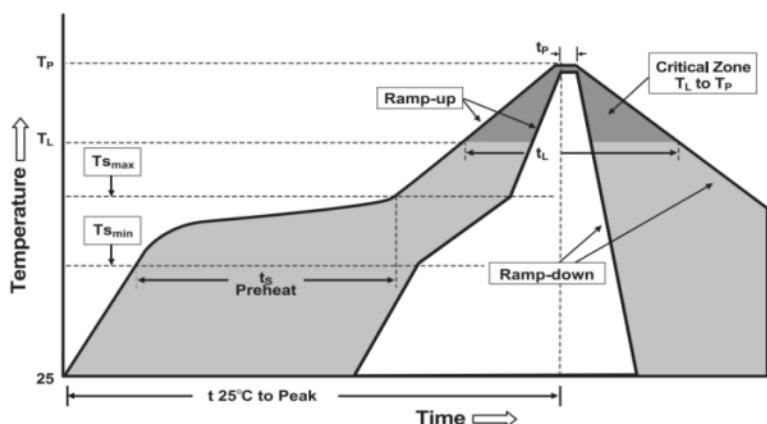
**Caution :** Operation beyond the specified rating may result in damage and possible arcing and flame. 注意：超出指定额定值的操作，可能会导致损伤并可能产生电弧和火焰。

**Product Dimensions(mm)/产品尺寸**

Part Number	Quantity	A		B		C		D	E
		Min	Max	Min	Max	Min	Max	Min	Min
1812L300/24GR	1500	-	4.73	-	3.41	-	0.90	0.30	0.30

**Temperature Derating/不同环境温度下的  $I_{hold}$  值**

Part Number	Ambient operating temperature hold current ( $I_{hold}$ )									
	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C
1812L300/24GR	4.41	3.99	3.44	3.07	3.00	2.65	2.31	2.16	1.84	1.43

**Solder Reflow Recommendations/回流焊建议**

Recommended Pad Layout (mm)

建议焊盘布局 (mm)

**Part Number System/产品编号**